

LTM8052 81LD -BGA-PBF 15mm X 11.25mm X 3.42mm-SOLDER DA (TABLE OF MATERIAL DECLARATION)

The LTM8052 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

| No. | Part Name | Material Name | Component Weight (gram) | Materials Analysis (element) | CAS Number | Material Mass (gram) | Materials Analysis (weight %) |
|----------------------|---------------------------|---------------|-------------------------|--|--|----------------------|-------------------------------|
| 1 | Substrate | Circuit Board | 0.1904 | Barium Compounds | 7727-43-7 | 0.00518 | 2.72 |
| | | | | Bismaleimide/Triazine/Resin/Filler Substance(Silica Crystalline) | 105391-33-1,1156-51-0/9003-36-5/21645-51-2 | 0.03485 | 18.31 |
| | | | | Copper Metal | 7440-50-8 | 0.12590 | 66.14 |
| | | | | Copper Compounds | 1328-53-6 | 0.00005 | 0.02 |
| | | | | Ecotoxic substances | 7440-38-2, 7440-28-0 | 0.00003 | 0.02 |
| | | | | Gold metal or alloy | 7440-57-5 | 0.00059 | 0.31 |
| | | | | Nickel | 7440-02-0 | 0.00381 | 2.00 |
| | | | | Zinc | 7440-66-6 | 0.00030 | 0.16 |
| | | | | Continuous Filament Fiber Glass | 65997-17-3 | 0.01892 | 9.94 |
| | | | | Chromium(III) Oxide | 1308-38-9 | 0.00001 | 0.01 |
| | | | | Silica amorphous | 7631-86-9 | 0.00011 | 0.06 |
| | | | | Talc;not containing fibers like asbestos | 14807-96-9 | 0.00059 | 0.31 |
| | | | | Cyanoguanidine | 461-58-5 | 0.00002 | 0.01 |
| | | | | Calcium caobonate | 471-34-1 | 0.00001 | 0.00 |
| 2 | Solder Paste | Alloy | 0.0301 | Sn | 7440-31-5 | 0.02859 | 95.00 |
| | | | | Sb | 7440-36-0 | 0.00150 | 5.00 |
| 3 | Passive/Active Components | | 0.5162 | Iron Powder (Fe) | 7439-89-6 | 0.28653 | 55.51 |
| | | | | Copper (Cu) | 7440-50-8 | 0.17996 | 34.86 |
| | | | | Nickel (Ni) | 7440-02-0 | 0.00684 | 1.33 |
| | | | | Tin (Sn) | 7440-31-5 | 0.00232 | 0.45 |
| | | | | Ceramic (Ba compounds) | 12047-27-7 | 0.04055 | 7.86 |
| 4 | Active Ics | Silicon | 0.0066 | Silicon | 7440-21-3 | 0.00655 | 100.00 |
| 5 | Wire | Gold | 0.0007 | Au | 7440-57-5 | 0.00070 | 99.99 |
| 6 | Solder Ball | SAC305 | 0.1363 | Sn | 7440-31-5 | 0.13153 | 96.50 |
| | | | | Ag | 7440-22-4 | 0.00409 | 3.00 |
| | | | | Cu | 7440-50-8 | 0.00068 | 0.50 |
| 7 | Encapsulation | Epoxy Resin | 0.6364 | Fused Silica | 60676-86-0 | 0.49126 | 77.20 |
| | | | | Epoxy Resin | non-disclosure | 0.05664 | 8.90 |
| | | | | Phenol Resin | non-disclosure | 0.05664 | 8.90 |
| | | | | Crytalline Silica | 14808-60-7 | 0.01909 | 3.00 |
| | | | | Carbon Black | 1333-86-4 | 0.00318 | 0.50 |
| | | | | Metal Hydroxide | non-disclosure | 0.00955 | 1.50 |
| Total Package Weight | | | 1.5165 | | | | |

Note: Composition derived from MSDS and material C of C from Vendors

Component Weight based on assembly of generic parts